L Number	Hits	Search Text	DB	Time stamp
1	9539	die near5 (attach or attaching or	USPAT;	2003/04/30 11:08
		attachment)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0003/04/30 11 00
2	10693	cyanoacrylate or cyano near2 acrylate	USPAT;	2003/04/30 11:08
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	65	(die near5 (attach or attaching or	USPĀT;	2003/04/30 11:59
ا		attachment)) and (cyanoacrylate or cyano	US-PGPUB;	
		near2 acrylate)	EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
4	28539	anaerobic	USPAT;	2003/04/30 11:59
		•	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/04/20 11:50
5	1226446	lead or leads	USPAT;	2003/04/30 11:59
		·	US-PGPUB; EPO; JPO;	
			DERWENT;	
j i			IBM TDB	
6	3722	leadframe	USPAT;	2003/04/30 12:03
"	3,22	Teachtaine	US-PGPUB;	=====================================
,			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
7	1227249	(lead or leads) or leadframe	USPAT;	2003/04/30 12:03
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/04/20 10:03
8	707	anaerobic same ((lead or leads) or	USPAT;	2003/04/30 12:03
		leadframe)	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
9	. 850838	adhesive or glue	USPAT;	2003/04/30 12:03
	. 030030	dunestive of grad	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	48	(anaerobic same ((lead or leads) or	USPAT;	2003/04/30 12:03
1		leadframe)) same (adhesive or glue)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
111	E00000	chin	IBM_TDB USPAT;	2003/04/30 12:03
11	528069	chip	USPAT; US-PGPUB;	2003/04/30 12:03
			EPO; JPO;	
			DERWENT;	
		· ·	IBM TDB	
12	406546	die	USPAT;	2003/04/30 12:04
	100010		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
13	891770	chip or die	USPAT;	2003/04/30 12:04
			US-PGPUB;	
			EPO; JPO;	
] .]		DERWENT;	
			IBM_TDB	2002/04/20 10 05
14	11	((anaerobic same ((lead or leads) or	USPĀT;	2003/04/30 12:05
		leadframe)) same (adhesive or glue)) and	US-PGPUB;	·
		(chip or die)	EPO; JPO;	
			DERWENT; IBM TDB	
L	L	<u> </u>	םתו הוחד	<u> </u>

L Number	Hits	Search Text	DB	Time stamp
1	3722	leadframe	USPAT;	2003/04/30 09:54
			US-PGPUB; EPO; JPO; DERWENT;	
2	535077	chip or semiconductor near5 die	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/30 09:55
3	2062	leadframe same (chip or semiconductor near5 die)	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/04/30 09:55
4	9601	cyanoacrylate	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/04/30 09:55
5	13	(leadframe same (chip or semiconductor near5 die)) and cyanoacrylate	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/04/30 10:07
6	62956	frame) near5(lead or leads	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/04/30 10:21
7	19589	(chip or semiconductor near5 die) same (frame) near5(lead or leads)	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/30 10:08
8	27	<pre>cyanoacrylate and ((chip or semiconductor near5 die) same (frame) near5(lead or leads))</pre>	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/30 10:19
9 10 11 12 13 14 15	1 24900 210 7 18811 1 62956	chip cyanoacrylate chip and cyanoacrylate semiconductor semiconductor and cyanoacrylate	DERWENT; IBM_TDB USOCR USOCR USOCR USOCR USOCR USOCR USOCR USOCR USOCR USPAT; US-PGPUB;	2003/04/30 10:19 2003/04/30 10:19 2003/04/30 10:19 2003/04/30 10:20 2003/04/30 10:20 2003/04/30 10:20 2003/04/30 10:22
16	3354585	bonded or attached or attaching or attachment or attach or bond or bonds or bonding	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/30 10:22
17	62956	frame near5(lead or leads)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/30 10:23
18	1594	(leadframe same (chip or semiconductor near5 die)) same (bonded or attached or attaching or attachment or attach or bond	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/30 10:23
19	850838	or bonds or bonding) adhesive or glue	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/04/30 10:23
			DERWENT; IBM TDB	

	411	I / (1 - 25 / - kin an and and at an	LICDAM.	2002/04/20 10.22
20	411		USPAT; US-PGPUB;	2003/04/30 10:23
		near5 die)) same (bonded or attached or	EPO; JPO;	
		attaching or attachment or attach or bond		1
		or bonds or bonding)) same (adhesive or	DERWENT; IBM TDB	
	146	glue)	USPAT;	2003/04/30 10:24
21	146	superglue	US-PGPUB;	2003/04/30 10:24
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	0	///landfrome come (ship or semicondustor	USPAT;	2003/04/30 10:24
22	1	(((leadframe same (chip or semiconductor near5 die)) same (bonded or attached or	US-PGPUB;	2003/04/30 10:21
		attaching or attachment or attach or bond	EPO; JPO;	
		or bonds or bonding)) same (adhesive or	DERWENT;	
		qlue)) and superglue	IBM TDB	
23	204456		USPAT;	2003/04/30 10:24
23	204430	delylace	US-PGPUB;	2000, 01, 00 20021
	1		EPO; JPO;	
			DERWENT;	
	}		IBM TDB	
24	211033	cyanoacrylate or acrylate	USPAT;	2003/04/30 10:24
~ .			US-PGPUB;	
	}		EPO; JPO;	
	1		DERWENT;	
	1		IBM TDB	
25	64	superglue and (cyanoacrylate or acrylate)	USPĀT;	2003/04/30 10:26
	}		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
26	10	, , , <u>-</u>	USPĀT;	2003/04/30 10:28
		near5 die)) same (bonded or attached or	US-PGPUB;	
		attaching or attachment or attach or bond	EPO; JPO;	
İ		or bonds or bonding)) same (adhesive or	DERWENT;	
1		glue)) and (cyanoacrylate or acrylate)	IBM_TDB	0000/04/00 10 00
27	7805	radiopaque	USPAT;	2003/04/30 10:29
	1		US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
28	0	radiopaque and (((leadframe same (chip or	USPAT;	2003/04/30 10:29
20		semiconductor near5 die) same (bonded or	US-PGPUB;	2003/04/30 10:23
		attached or attaching or attachment or	EPO; JPO;	
		attach or bond or bonds or bonding)) same	DERWENT;	
		(adhesive or glue))	IBM TDB	
29	0	1	USPAT;	2003/04/30 10:29
	I	semiconductor near5 die))	US-PGPUB;	
			EPO; JPO;	
		·	DERWENT;	
			IBM TDB	
30	606	radiopaque and cyanoacrylate	USPĀT;	2003/04/30 10:30
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
31	0		USPĀT;	2003/04/30 10:30
		leadframe	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	,
			IBM_TDB	
32	0		USPAT;	2003/04/30 10:30
		near5(lead or leads))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	<u></u>		IBM TDB	

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Γ	15	451	1 , , ,	USPAT;	2003/04/30 08:24
1			semiconductor) and (adhesive same	US-PGPUB;	
ı			acrylate)	EPO; JPO;	
1				DERWENT;	
1				IBM_TDB	
ı	16	1	adhasive same cyanoacrylate	USPAT;	2003/04/30 08:25
				US-PGPUB;	
İ				EPO; JPO;	
				DERWENT;	l I
				IBM TDB	
	17	5418	adhesive same cyanoacrylate	USPAT;	2003/04/30 08:25
1	Ι,	0120		US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
				IBM TDB	
	18	528069	chip .	USPAT;	2003/04/30 08:25
	10] 320003	Chip .	US-PGPUB;	2000, 01, 00 00120
				EPO; JPO;	
				DERWENT;	
				IBM TDB	
	19	51.	(adhesive same cyanoacrylate) same chip	USPAT;	2003/04/30 08:26
	19	"	(admestive same cyanoactytate) same chip	US-PGPUB;	2003,01,30 00.20
				EPO; JPO;	
				DERWENT;	
				IBM TDB	
	20	5830	fast near7 (cure or curing or cured or	USPAT;	2003/04/30 08:27
	20	3630	cures)	US-PGPUB;	2003/04/30 00:27
			Cules/	EPO; JPO;	
				DERWENT;	
				IBM TDB	
	21	2212	quick near7 (cure or curing or cured or	USPAT;	2003/04/30 08:27
	C 1	2212	cures)	US-PGPUB;	2003/04/30 00:27
			Cures	EPO; JPO;	
				DERWENT;	
			·	IBM TDB	
	22	7842	 (fast near7 (cure or curing or cured or	USPAT;	2003/04/30 08:27
	44	/042	cures)) or (quick near7 (cure or curing or	US-PGPUB;	2003/04/30 00:27
			cured or cures))	EPO; JPO;	
			cured of cures//	DERWENT;	
				IBM TDB	
	23	2	((fast near7 (cure or curing or cured or	USPAT;	2003/04/30 08:27
	23		cures)) or (quick near7 (cure or curing or	US-PGPUB;	2003/04/30 06:27
			cures)) or (quick hear) (cure or curing or cured or cures))) and ((adhesive same	EPO; JPO;	
				DERWENT;	
			cyanoacrylate) same chip)	TBM TDB	
1	l l	ı	l .	I TOM IND	1

L Number	Hits	Search Text	DB	Time stamp
1	9601	cyanoacrylate	USPAT;	2003/04/30 08:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/04/00 00 17
2	1227249	lead or leads or leadframe	USPAT;	2003/04/30 08:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
3	2719	cyanoacrylate and (lead or leads or	USPAT;	2003/04/30 08:18
3	2/19	leadframe)	US-PGPUB;	2003, 01, 00 00, 20
		Tours of the state	EPO; JPO;	
		·	DERWENT;	
			IBM TDB	
4	286	cyanoacrylate same (lead or leads or	USPĀT;	2003/04/30 08:18
	ı	leadframe)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	1226446	lead or leads	USPAT;	2003/04/30 08:18
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	305	guarante dama (load am loads)	IBM_TDB USPAT;	2003/04/30 08:19
6	285	cyanoacrylate same (lead or leads)	USPAT; US-PGPUB;	2003/04/30 00:19
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	1220310	semiconductor	USPAT;	2003/04/30 08:19
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	26	(cyanoacrylate same (lead or leads)) and	USPAT;	2003/04/30 08:19
		semiconductor	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
9	3722	leadframe	USPAT;	2003/04/30 08:19
	3122	TeadItaile	US-PGPUB;	2003/04/30 00:13
			EPO; JPO;	
.		,	DERWENT;	
[IBM TDB	
10	5	leadframe and ((cyanoacrylate same (lead	USPAT;	2003/04/30 08:23
		or leads)) and semiconductor)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	000010:155
11	204456	acrylate	USPĀT;	2003/04/30 08:23
			US-PGPUB;	
	•		EPO; JPO;	
			DERWENT; IBM TDB	
12	39108	(lead or leads) and acrylate	USPAT;	2003/04/30 08:23
1 14	23108	(read of reads) and activiate	US-PGPUB;	2003/04/30 00:23
			EPO; JPO;	
			DERWENT;	·
			IBM TDB	
13	3408	((lead or leads) and acrylate) and	USPAT;	2003/04/30 08:24
		semiconductor	US-PGPUB;	
			EPO; JPO;	•
			DERWENT;	
			IBM_TDB	
14	21332	adhesive same acrylate	USPAT;	2003/04/30 08:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
L			IBM TDB	